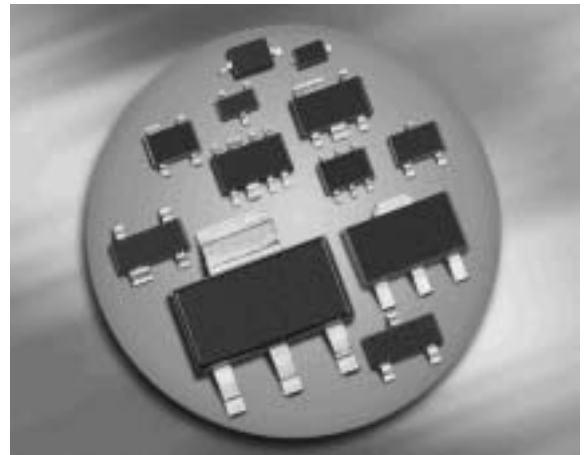
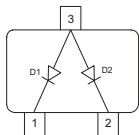


Silicon Switching Diode

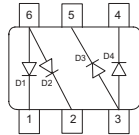
- For high-speed switching applications
- Common anode configuration
- BAW56S / U: For orientation in reel see package information below
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101



BAW56 BAW56W



BAW56S BAW56U



Type	Package	Configuration	Marking
BAW56	SOT23	common anode	A1s
BAW56S	SOT363	double common anode	A1s
BAW56U	SC74	double common anode	A1s
BAW56W	SOT323	common anode	A1s

¹⁾Pb-containing package may be available upon special request

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	80	V
Peak reverse voltage	V_{RM}	85	
Forward current	I_F	200	mA
Non-repetitive peak surge forward current	I_{FSM}		A
$t = 1 \mu\text{s}$		4.5	
$t = 1 \text{ ms}$		1	
$t = 1 \text{ s, single}$		0.5	
$t = 1 \text{ s, double}$		0.75	
Total power dissipation	P_{tot}		mW
BAW56, $T_S \leq 28^\circ\text{C}$		330	
BAW56S, $T_S \leq 85^\circ\text{C}$		250	
BAW56U, $T_S \leq 90^\circ\text{C}$		250	
BAW56W, $T_S \leq 103^\circ\text{C}$		250	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BAW56		360	
BAW56S		260	
BAW56U		240	
BAW56W		190	

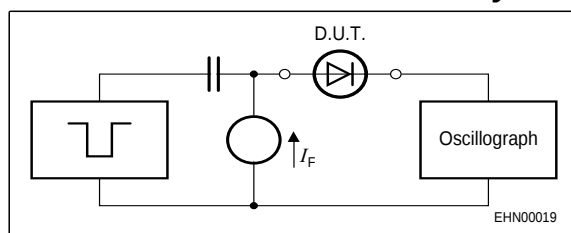
¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{\text{(BR)}} = 100\text{ }\mu\text{A}$	$V_{\text{(BR)}}$	85	-	-	V
Reverse current $V_{\text{R}} = 70\text{ V}$ $V_{\text{R}} = 25\text{ V}, T_{\text{A}} = 150\text{ }^{\circ}\text{C}$ $V_{\text{R}} = 70\text{ V}, T_{\text{A}} = 150\text{ }^{\circ}\text{C}$	I_{R}	- - -	- - -	0.15 30 50	μA
Forward voltage $I_{\text{F}} = 1\text{ mA}$ $I_{\text{F}} = 10\text{ mA}$ $I_{\text{F}} = 50\text{ mA}$ $I_{\text{F}} = 100\text{ mA}$ $I_{\text{F}} = 150\text{ mA}$	V_{F}	- - - - -	- - - - -	715 855 1000 1200 1250	mV

AC Characteristics

Diode capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_T	-	-	2	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}$, measured at $I_R = 1 \text{ mA}$, $R_L = 100 \Omega$	t_{rr}	-	-	4	ns

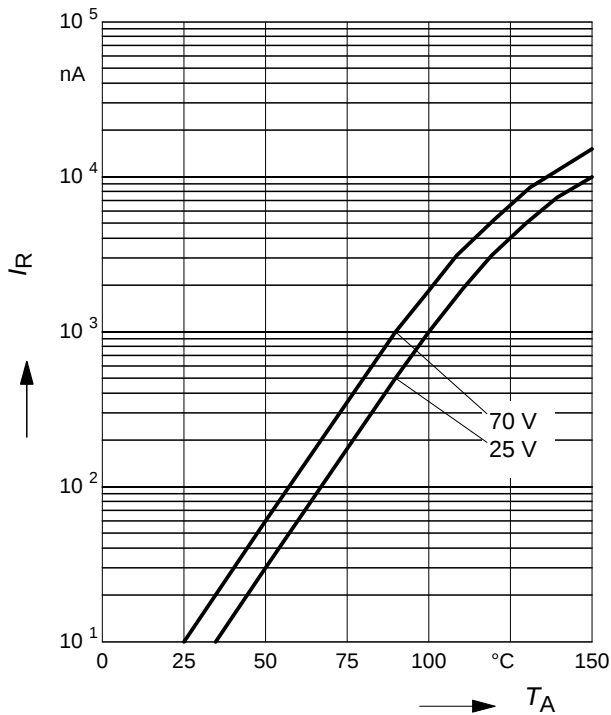
Test circuit for reverse recovery time


Pulse generator: $t_p = 100 \text{ ns}$, $D = 0.05$, $t_r = 0.6 \text{ ns}$,
 $R_i = 50 \Omega$

Oscilloscope: $R = 50 \Omega$, $t_r = 0.35 \text{ ns}$, $C \leq 1 \text{ pF}$

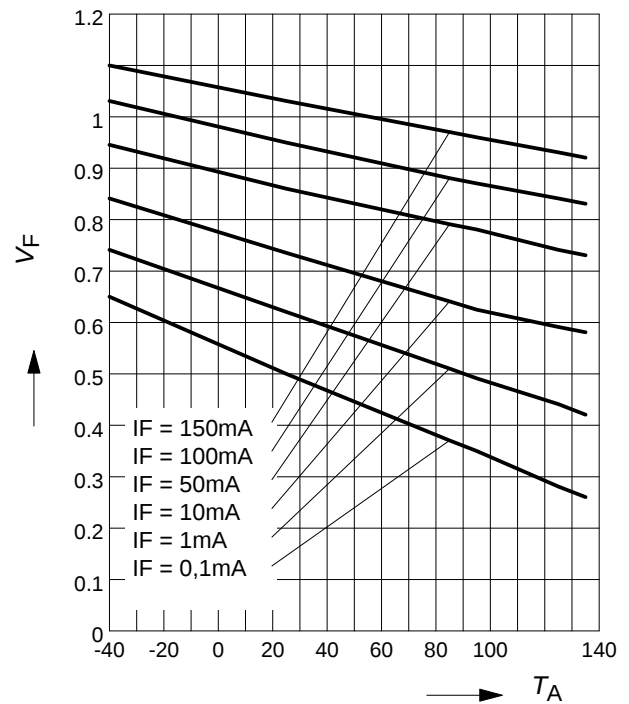
Reverse current $I_R = f(T_A)$

$V_R = \text{Parameter}$



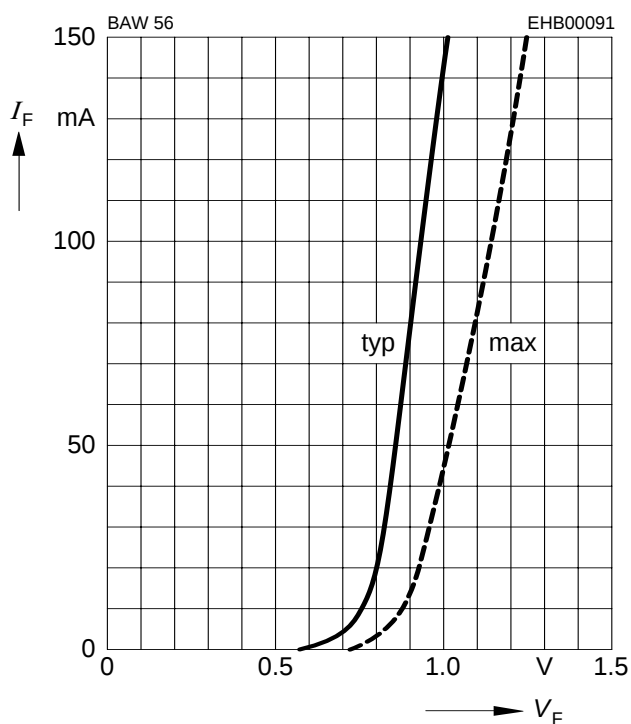
Forward Voltage $V_F = f(T_A)$

$I_F = \text{Parameter}$



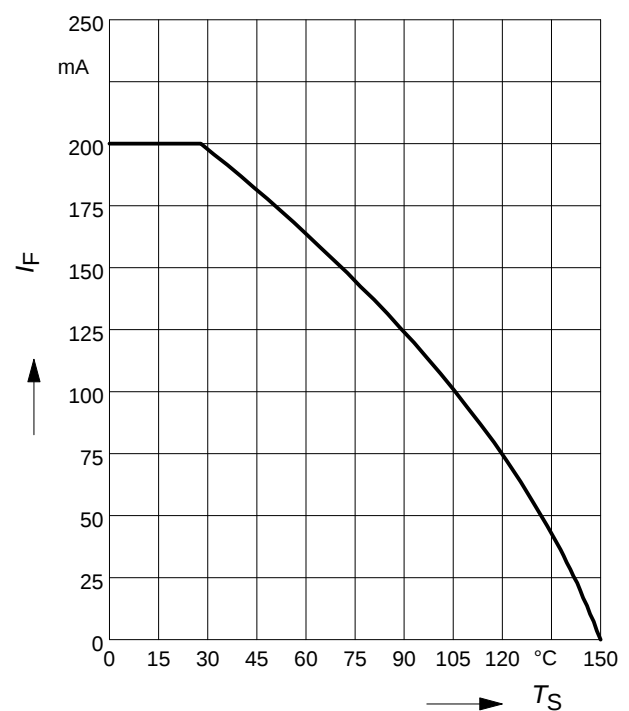
Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



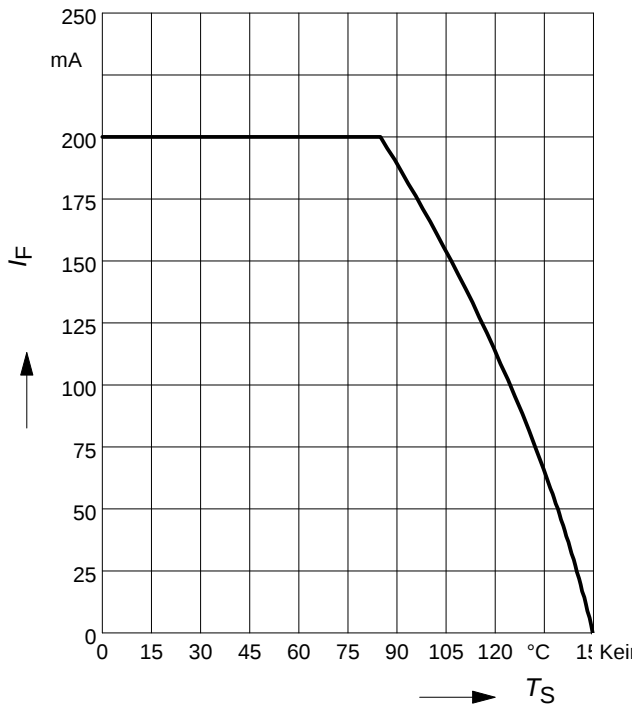
Forward current $I_F = f(T_S)$

BAW56



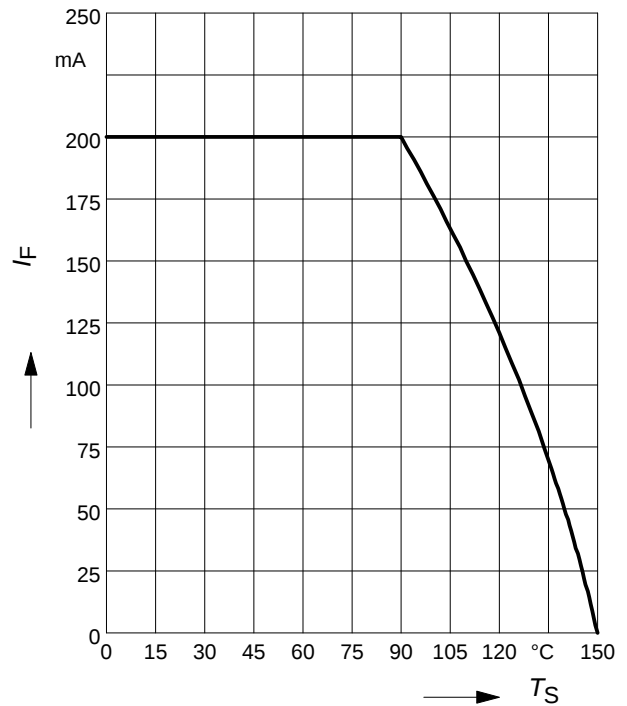
Forward current $I_F = f(T_S)$

BAW56S



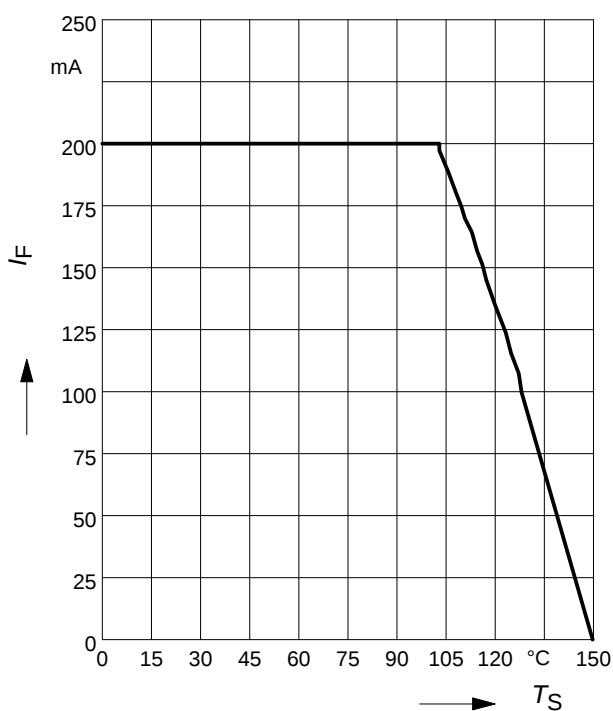
Forward current $I_F = f(T_S)$

BAW56U



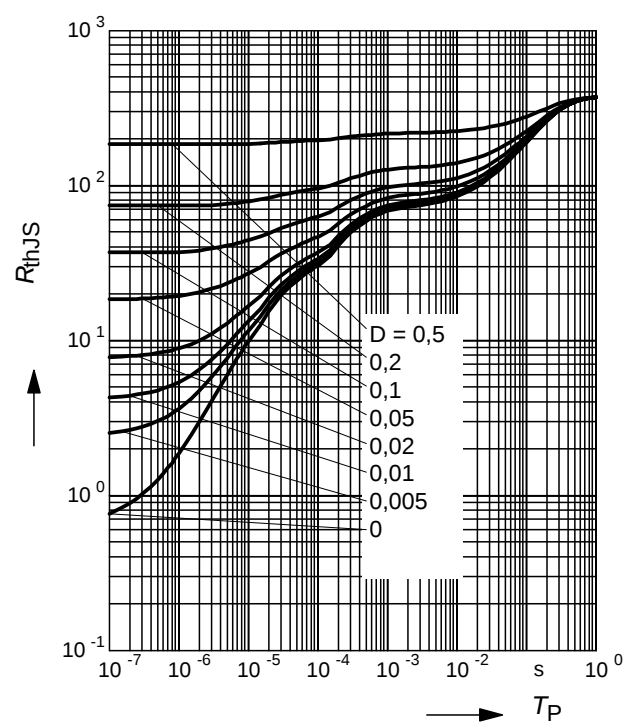
Forward current $I_F = f(T_S)$

BAW56W



Permissible Puls Load $R_{thJS} = f(t_p)$

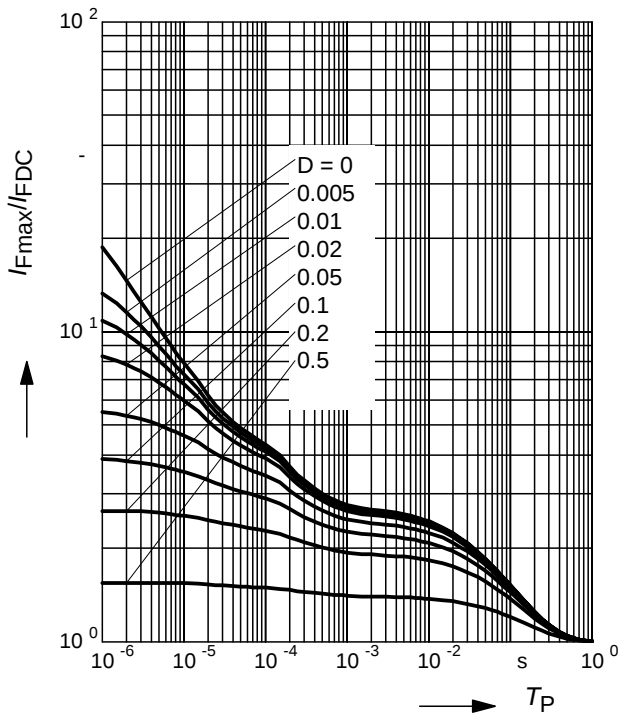
BAW56



Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAW56



Permissible Puls Load $R_{thJS} = f(t_p)$

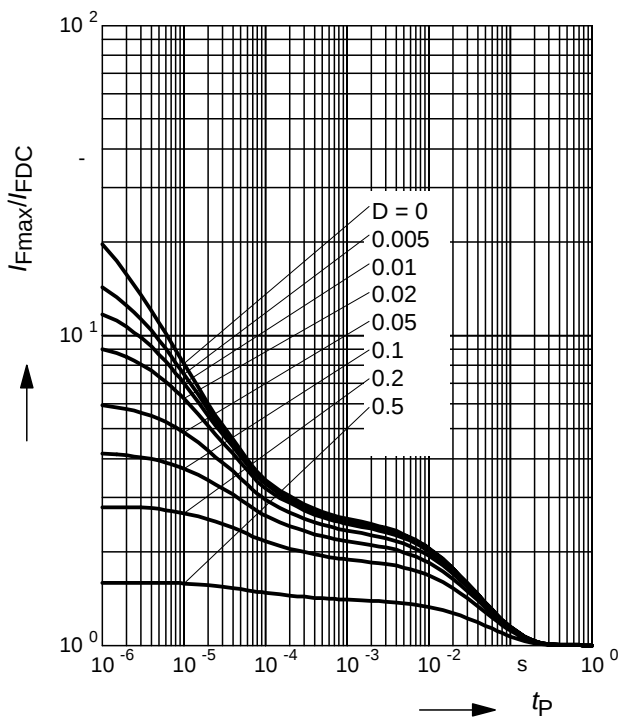
BAW56S



Permissible Pulse Load

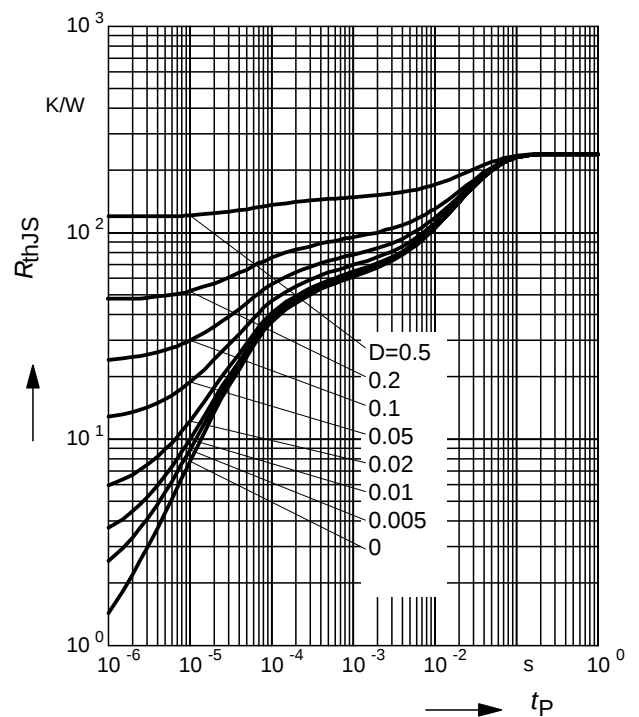
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAW56S



Permissible Puls Load $R_{thJS} = f(t_p)$

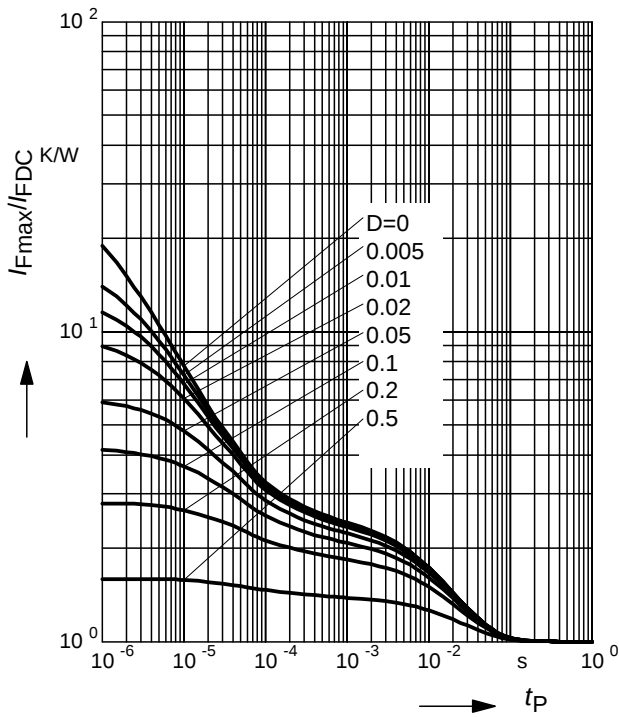
BAW56U



Permissible Pulse Load

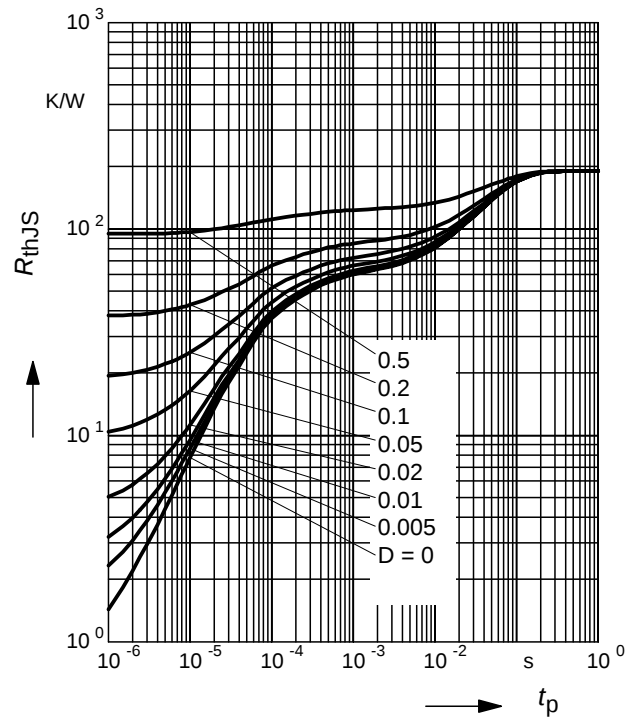
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAW56U



Permissible Puls Load $R_{thJS} = f(t_p)$

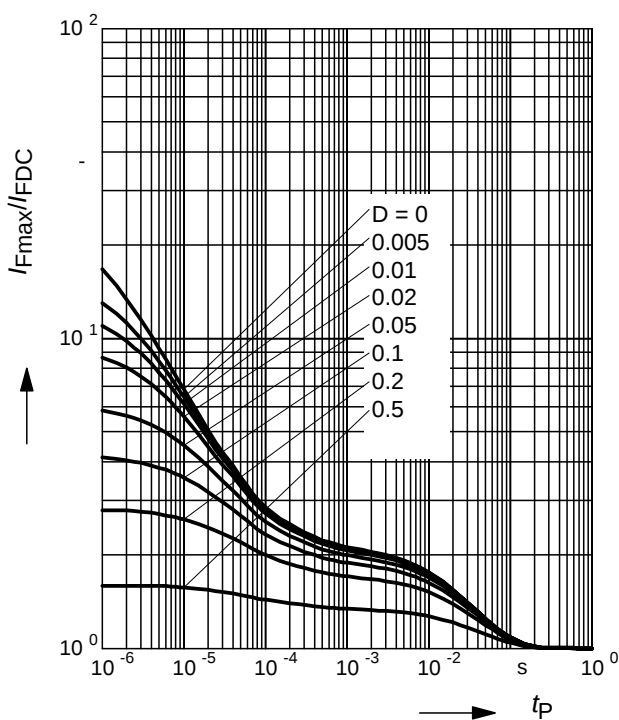
BAW56W



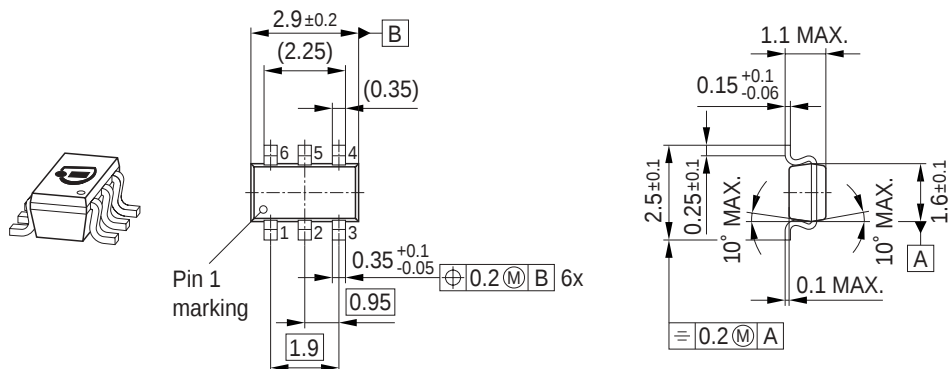
Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

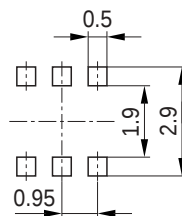
BAW56W



Package Outline

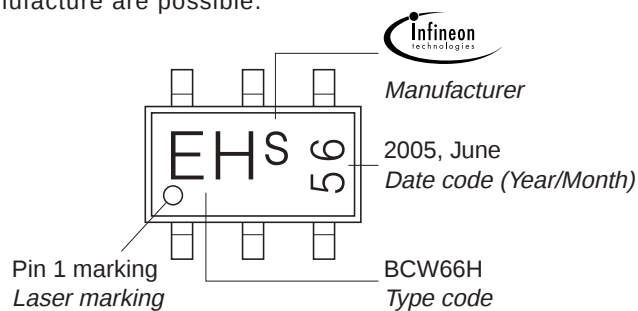


Foot Print



Marking Layout (Example)

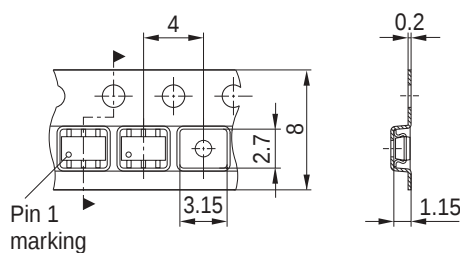
Small variations in positioning of Date code, Type code and Manufacture are possible.



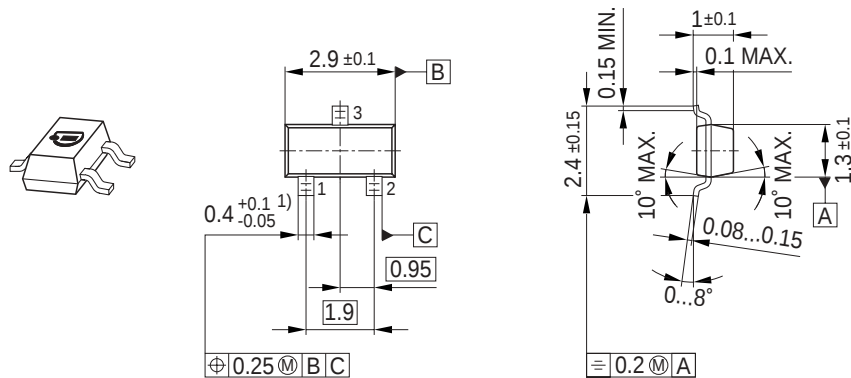
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

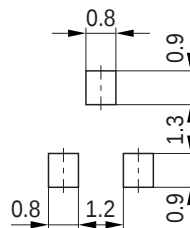


Package Outline

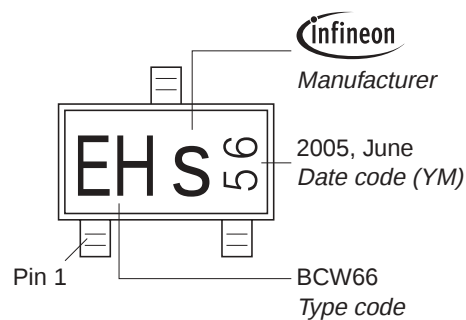


1) Lead width can be 0.6 max. in dambar area

Foot Print

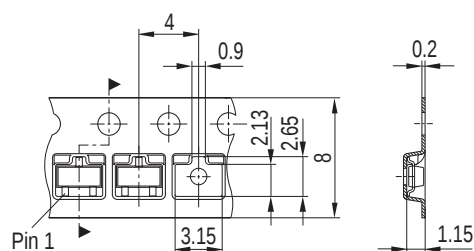


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



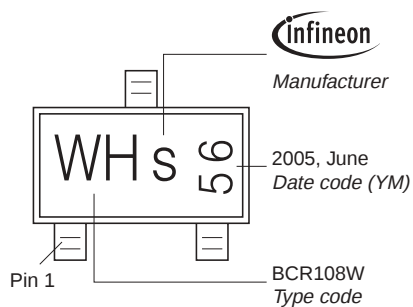
Package Outline



Foot Print



Marking Layout (Example)

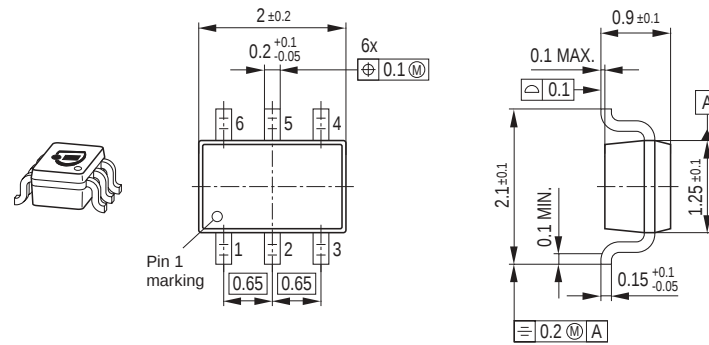


Standard Packing

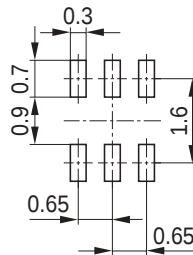
Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



Package Outline



Foot Print



Marking Layout (Example)

Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
Reel $\varnothing 330$ mm = 10.000 Pieces/Reel

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